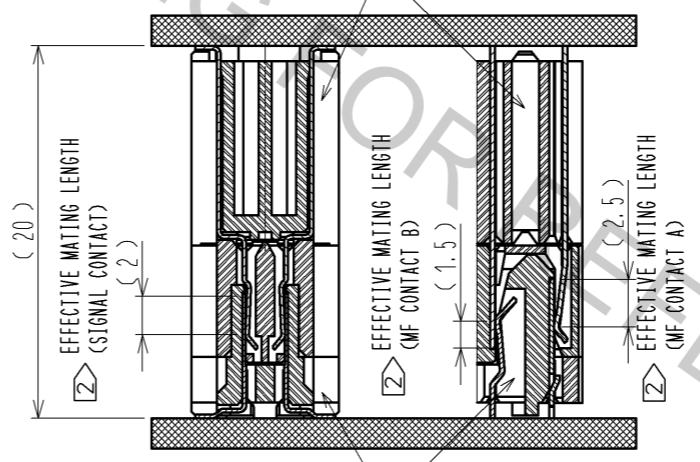
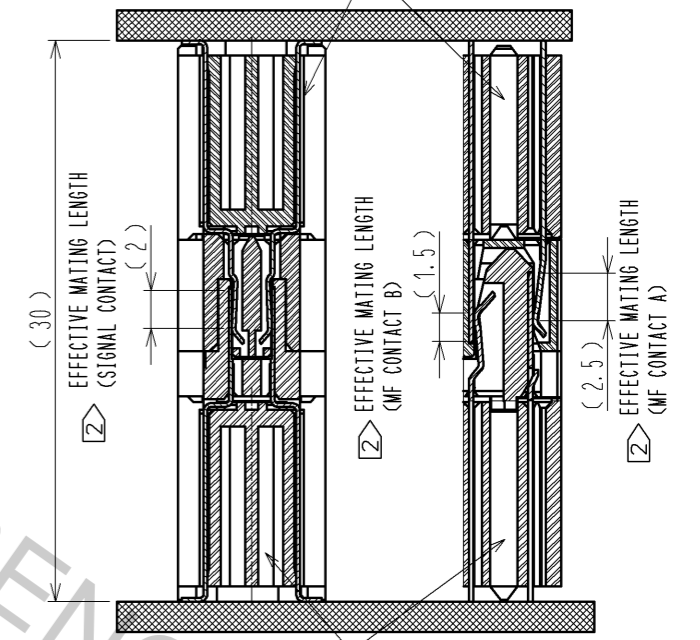


CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=20mm
FX18-40S-0.8SV20



CROSS SECTION OF MATING(FREE)
STACKING HEIGHT=30mm
FX18-40S-0.8SV20

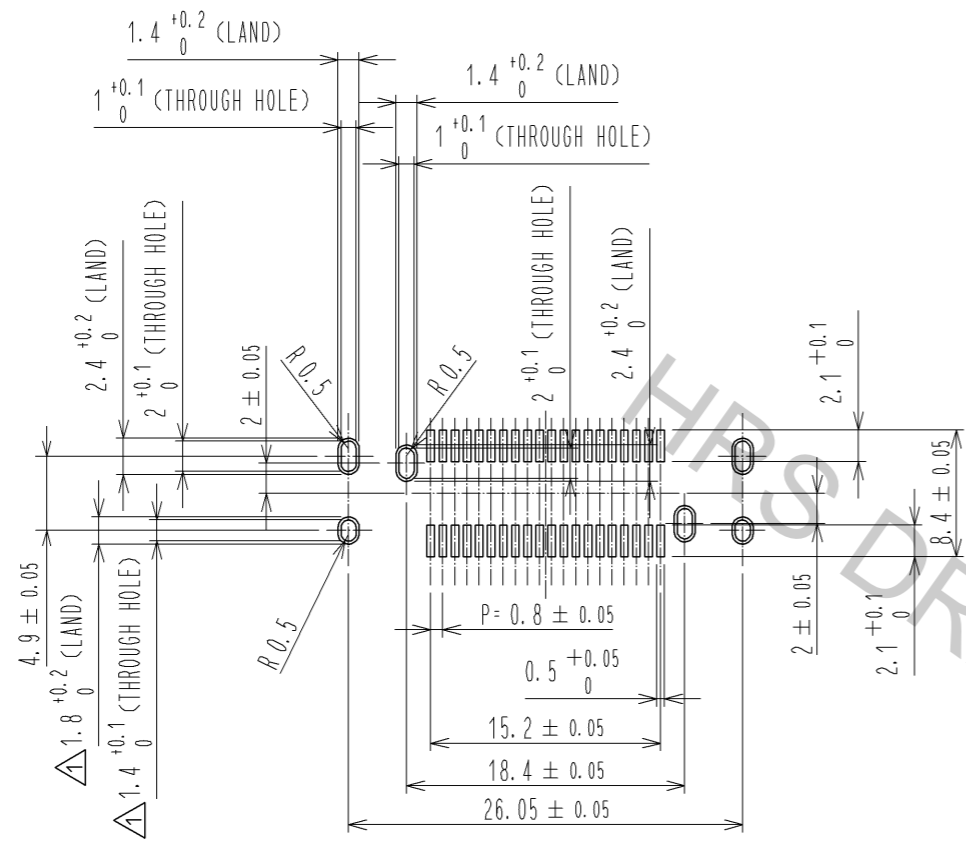


- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 4 IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
 REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
 5 THIS IS PACKAGED IN TRAY. (60pcs/TRAY)
 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm	5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
2	POLYAMIDE	BLACK UL94V-0	4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm
1	POLYAMIDE	BLACK UL94V-0			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS

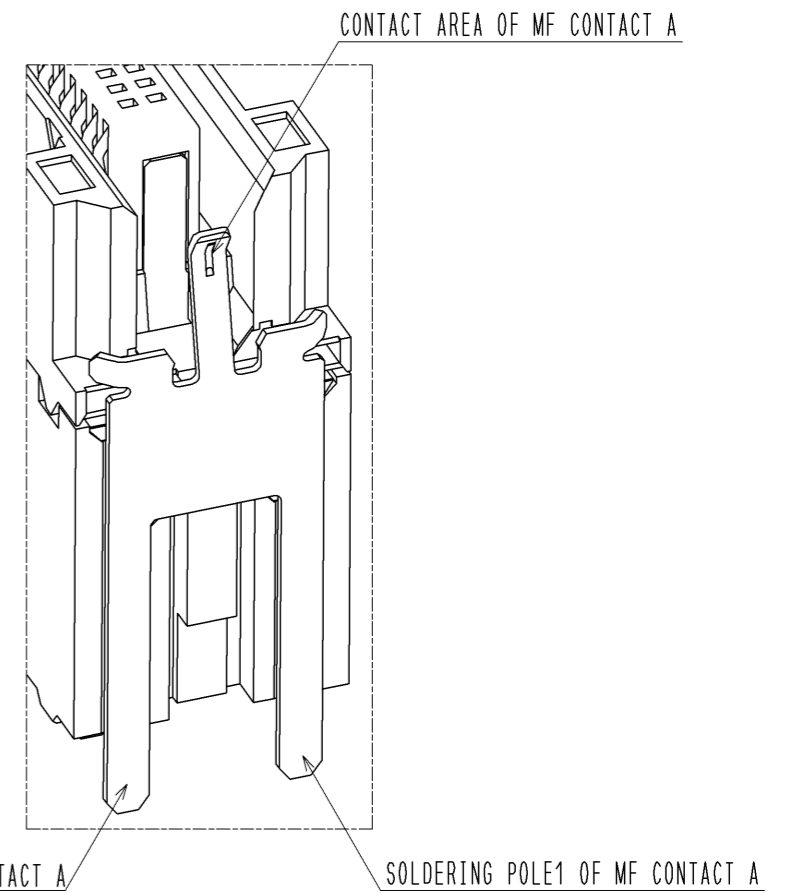
UNITS	mm	SCALE	2 : 1	COUNT	4	DESCRIPTION OF REVISIONS	DESIGNED	TH. SANO	CHECKED	KI. HIROKAWA	DATE	11.07.21
APPROVED : HS. OKAWA		11.03.18		DRAWING NO.		EDC3-334390-00						
CHECKED : KI. HIROKAWA		11.03.18		PART NO.		FX18-40S-0.8SV20						
DESIGNED : TH. SANO		11.03.18		CODE NO.		CL579-0030-0-00						
DRAWN : TH. SANO		11.03.18										

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

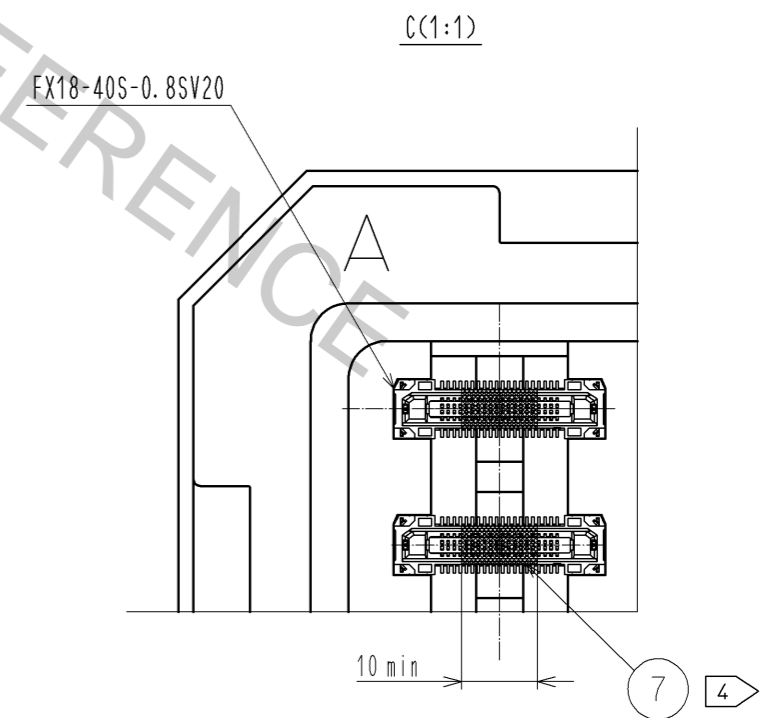
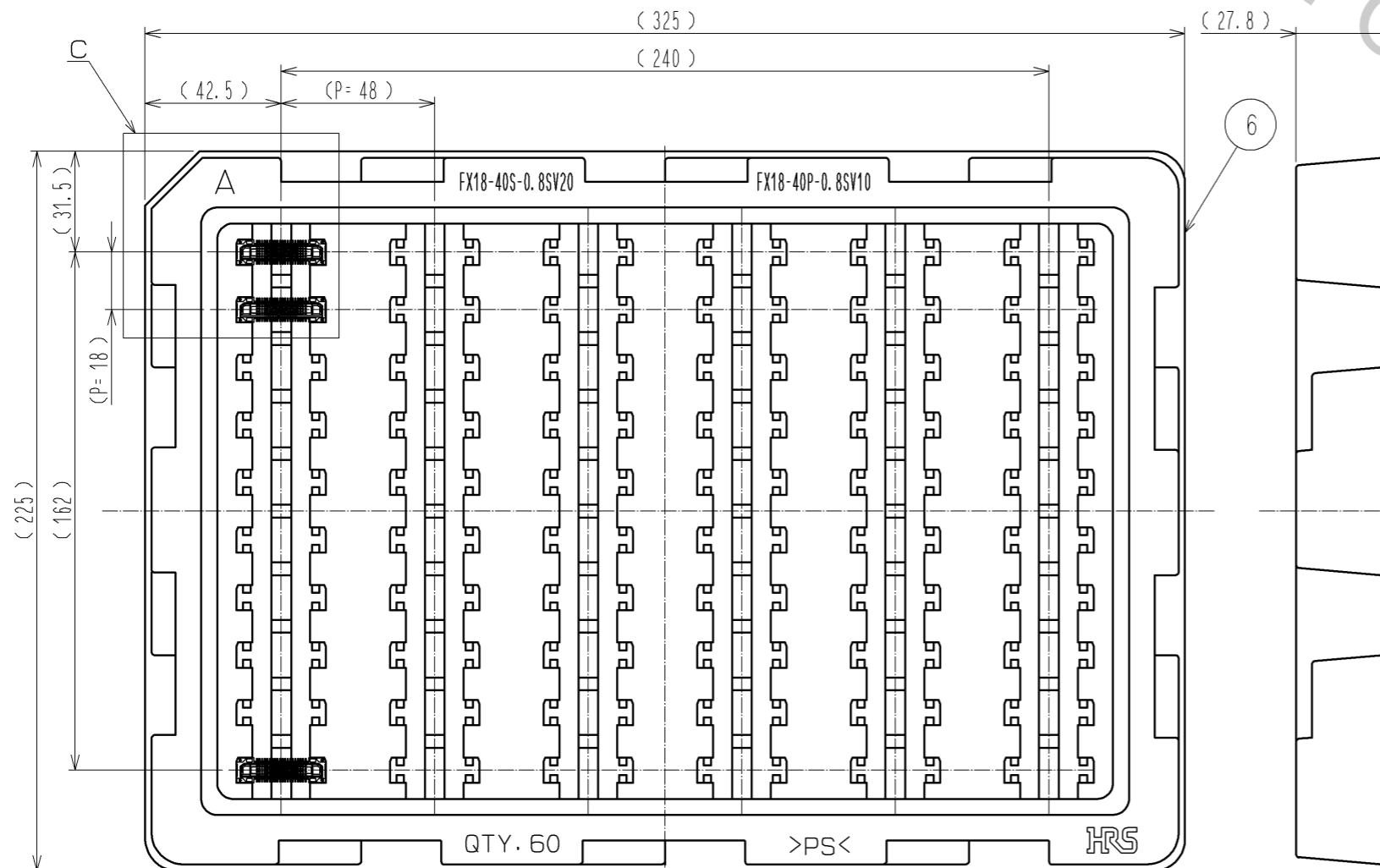


5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.



HRS	DRAWING NO.	EDC3-334390-00	1/2
	PART NO.	FX18-40S-0.8SV20	
	CODE NO.	CL579-0030-0-00	